

FAST RECOVERY DIODE

- Junction Size: Square 230 mils
- Wafer Size: 4"
- V_{RRM} Class: 600 V
- Passivation Process: Glassivated MOAT
- Reference IR Packaged Part: 40EPF Series

Major Ratings and Characteristics

Parameters	Units	Test Conditions
V_{FM} Maximum Forward Voltage	1080mV	$T_J = 25^\circ\text{C}$, $I_F = 20\text{ A}$
V_{RRM} Reverse Breakdown Voltage	600V	$T_J = 25^\circ\text{C}$, $I_{RRM} = 100\text{ }\mu\text{A}$ (1)
t_{rr} Reverse Recovery Time	60ns	$T_J = 25^\circ\text{C}$, $I_F = 1\text{ A}$, $-di/dt = 100\text{ A}/\mu\text{s}$

(1) Nitrogen flow on die edge.

Mechanical Characteristics

Nominal Back Metal Composition, Thickness	Cr - Ni - Ag (1 KA - 4 KA - 6 KA)
Nominal Front Metal Composition, Thickness	100% Al, (20 μm)
Chip Dimensions	230 x 230 mils (see drawing)
Wafer Diameter	100 mm, with std. < 110 > flat
Wafer Thickness	300 μm , $\pm 10\text{ }\mu\text{m}$
Maximum Width of Sawing Line	45 μm
Reject Ink Dot Size	0.25 mm diameter minimum
Ink Dot Location	See drawing
Recommended Storage Environment	Storage in original container, in dessicated nitrogen, with no contamination

IR230LM06CS02CB

Bulletin I0126J 08/97

International
IR Rectifier

Ordering Information Table

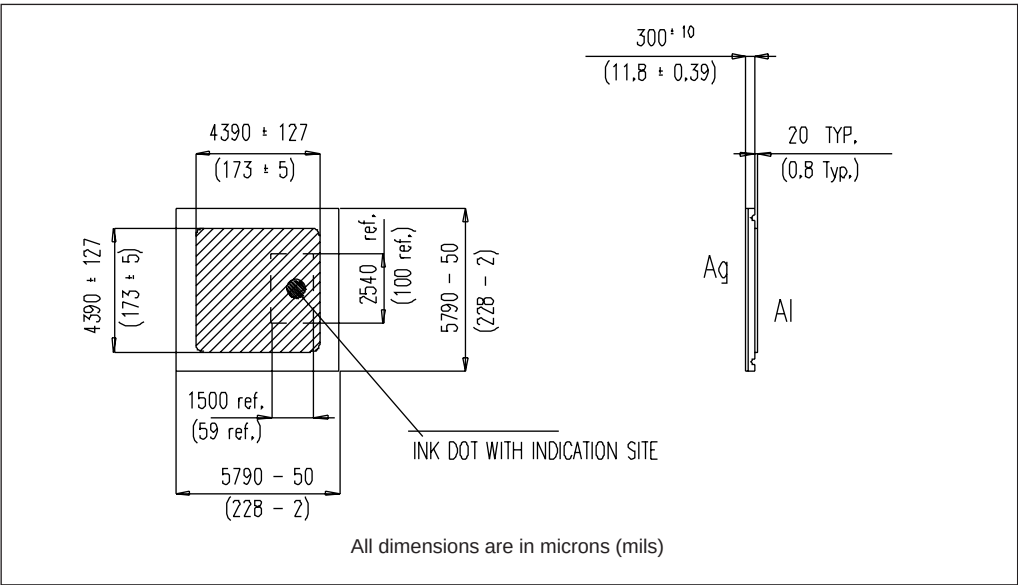
Device Code

IR	230	L	M	06	C	S02	CB
1	2	3	4	5	6	7	8

1	- International Rectifier Device
2	- Chip Dimension in Mils
3	- Type of Device: L = Wire Bondable Fast Recovery Diode
4	- Passivation Process: M = Glassivated MOAT
5	- Voltage code: Code x 100 = V_{RRM}
6	- Metallization: C = Aluminium (Anode) - Silver (Cathode)
7	- t_{rr} code: S02 = 60 nsec
8	- CB = Probed Uncut Die (wafer in box)

None = Probed Die in chip carrier

Outline Table



Wafer Layout

